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FMS6404
Precision Composite Video Output with Sound Trap and Group Delay Compensation

Features
- 7.6MHz 5th-Order Composite Video Filter
- 14dB Notch at 4.25MHz to 4.6MHz for Sound Trap Capable of Handling Stereo
- 50dB Stopband Attenuation at 27MHz on CV Output
- > 0.5dB Flatness to 4.2MHz on CV Output
- Equalizer and Notch Filter for Driving RF Modulator with Group Delay of -180ns
- No External Frequency Selection Components or Clocks
- < 5ns Group Delay on CV Output
- AC-Coupled Input
- AC- or DC-Coupled Output
- Capable of PAL Frequency for CV
- Continuous Time Low-Pass Filters
- <1.4% Differential Gain with 0.7° Differential Phase on CV Channel
- Integrated DC Restore Circuitry with Low Tilt

Applications
- Cable Set-Top Boxes
- Satellite Set-Top Boxes
- DVD Players

Description
The FMS6404 is a single composite video 5th-order Butterworth low-pass video filter optimized for minimum overshoot and flat group delay. The device contains an audio trap that removes video information in a spectral location of the subsequent RF audio carrier. The group delay compensation circuit pre-distorts the signal to compensate for the inherent receiver intermediate frequency (IF) filter’s group delay distortion.

In a typical application, the composite video from the DAC is AC coupled into the filter. The CV input has DC restore circuitry to clamp the DC input levels during video synchronization. The clamp pulse is derived from the CV channel.

All outputs are capable of driving 2V_{PP}, AC- or DC-coupled, into either a single or dual video load. A single video load consists of a series 75Ω impedance matching resistor connected to a terminated 75Ω line. This presents a total of 150Ω of loading to the part. A dual load would be two of these in parallel, which presents a total of 75Ω to the part. The gain of the CV signal is 6dB with 1V_{PP} input levels. All video channels are clamped during synchronization to establish the appropriate output voltage reference levels.

Related Resources
- AN-6024 – FMS6xxx Product Series Understanding Analog Video Signal Clamps, Bias, DC Restore, and AC or DC coupling Methods
- AN-6041 – PCB Layout Considerations for Video Filter / Drivers

Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Operating Temperature Range</th>
<th>Package</th>
<th>Packing Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>FMS6404CSX</td>
<td>-40°C to +70°C</td>
<td>8-Lead, Small-Outline Integrated Circuit (SOIC), JEDEC MS-012, .150&quot; Narrow Body</td>
<td>2500 Units per Reel</td>
</tr>
</tbody>
</table>
**Block Diagram**

![Block Diagram](image)

Figure 1. Block Diagram

**Pin Configuration**

![Pin Assignments](image)

Figure 2. Pin Assignments (Top View)

**Pin Definitions**

<table>
<thead>
<tr>
<th>Pin#</th>
<th>Name</th>
<th>Type</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>CV In</td>
<td>Input</td>
<td>Composite video input</td>
</tr>
<tr>
<td>2</td>
<td>EQ_Notch</td>
<td>Output</td>
<td>Composite video output to RF modulator</td>
</tr>
<tr>
<td>3</td>
<td>GND</td>
<td>Power</td>
<td>Device ground connection</td>
</tr>
<tr>
<td>4</td>
<td>NC</td>
<td>NA</td>
<td>No connection</td>
</tr>
<tr>
<td>5</td>
<td>NC</td>
<td>NA</td>
<td>No connection</td>
</tr>
<tr>
<td>6</td>
<td>NC</td>
<td>NA</td>
<td>No connection</td>
</tr>
<tr>
<td>7</td>
<td>Vcc</td>
<td>Power</td>
<td>Device power connection</td>
</tr>
<tr>
<td>8</td>
<td>CV Out</td>
<td>Output</td>
<td>Composite video output</td>
</tr>
</tbody>
</table>
Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC</td>
<td>DC Supply Voltage</td>
<td>-0.3</td>
<td>6.0</td>
<td>V</td>
</tr>
<tr>
<td>VIO</td>
<td>Analog and Digital I/O</td>
<td>-0.3</td>
<td>VCC+0.3</td>
<td>V</td>
</tr>
<tr>
<td>VOUT</td>
<td>Maximum Output Current, Do Not Exceed</td>
<td>100</td>
<td></td>
<td>mA</td>
</tr>
</tbody>
</table>

Electrostatic Discharge Information

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>ESD</td>
<td>Human Body Model, JESD22-A114</td>
<td>8</td>
<td>kV</td>
</tr>
<tr>
<td></td>
<td>Charged Device Model, JESD22-C101</td>
<td>2</td>
<td>kW</td>
</tr>
</tbody>
</table>

Reliability Information

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Tj</td>
<td>Junction Temperature</td>
<td></td>
<td>+150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>TSTG</td>
<td>Storage Temperature Range</td>
<td>-65</td>
<td>+150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>TL</td>
<td>Lead Temperature (Soldering, 10 Seconds)</td>
<td></td>
<td>+300</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>JA</td>
<td>Thermal Resistance, JEDEC Standard, Multilayer Test Board, Still Air</td>
<td>90</td>
<td></td>
<td>°C/W</td>
<td></td>
</tr>
</tbody>
</table>

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>TA</td>
<td>Operating Temperature Range</td>
<td></td>
<td>+70</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>VCC</td>
<td>Supply Voltage Range</td>
<td>4.75</td>
<td>5.00</td>
<td>5.25</td>
<td>V</td>
</tr>
</tbody>
</table>

DC Electrical Characteristics

T<sub>A</sub>=25°C, V<sub>CC</sub>=5.0V, R<sub>0</sub>=37.5Ω, all inputs are AC-coupled with 0.1µF, and all outputs are AC coupled with 220µF into 150Ω load; unless otherwise noted.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Condition</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC</td>
<td>Supply Voltage Range</td>
<td>V&lt;sub&gt;S&lt;/sub&gt; Range</td>
<td>4.75</td>
<td>5.00</td>
<td>5.25</td>
<td>V</td>
</tr>
<tr>
<td>ICC</td>
<td>Quiescent Supply Current</td>
<td>V&lt;sub&gt;S&lt;/sub&gt;=+5.0V, No Load</td>
<td>50</td>
<td>70</td>
<td>90</td>
<td>mA</td>
</tr>
<tr>
<td>VIN</td>
<td>Video Input Voltage Range</td>
<td>Referenced to GND if DC Coupled</td>
<td>1.4</td>
<td>V&lt;sub&gt;PP&lt;/sub&gt;</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PSRR</td>
<td>Power Supply Rejection Ratio</td>
<td>DC</td>
<td>-50</td>
<td></td>
<td>dB</td>
<td></td>
</tr>
<tr>
<td>ISC</td>
<td>Output Short Circuit Current</td>
<td>CV, EQ_NOTCH to GND</td>
<td>85</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
</tbody>
</table>
AC Electrical Characteristics

$T_a=25^\circ C$, $V_{CC}=5.0V$, $R_S=37.5\Omega$, all inputs are AC-coupled with 0.1µF, and all outputs are AC coupled with 220µF into 150Ω load, unless otherwise noted.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Condition</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$A_{VC}$</td>
<td>Low Frequency Gain CVOUT</td>
<td>at 400kHz</td>
<td>5.8</td>
<td>6.0</td>
<td>6.2</td>
<td>dB</td>
</tr>
<tr>
<td>$A_{VE}$</td>
<td>Low Frequency Gain (EQ_NOTCH)</td>
<td>at 400kHz</td>
<td>5.7</td>
<td>6.0</td>
<td>6.4</td>
<td>dB</td>
</tr>
<tr>
<td>$CV_{sync}$</td>
<td>CVOUT Output Level (During Sync)</td>
<td>Sync Present on CVIN (After 6dB Gain)</td>
<td>0.35</td>
<td>0.50</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>$EQ_{sync}$</td>
<td>EQ_NOTCH Output Level (During Sync)</td>
<td>Sync Present on CVIN (After 6dB Gain)</td>
<td>0.35</td>
<td>0.50</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>$t_{CLAMP}$</td>
<td>Clamp Response Time CVOUT</td>
<td>Settled to within 10mV</td>
<td></td>
<td>5</td>
<td></td>
<td>ms</td>
</tr>
<tr>
<td>$f_{FLAT}$</td>
<td>Gain Flatness to 4.2MHz CVOUT</td>
<td></td>
<td>-0.5</td>
<td>0</td>
<td>0.5</td>
<td>dB</td>
</tr>
<tr>
<td>$f_C$</td>
<td>-3dB Bandwidth CVOUT Channel</td>
<td></td>
<td>6.7</td>
<td>7.6</td>
<td></td>
<td>MHz</td>
</tr>
<tr>
<td>$f_{SB}$</td>
<td>Stopband Attenuation CVOUT</td>
<td>at 27MHz</td>
<td>40</td>
<td>50</td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>$dG$</td>
<td>Differential Gain CVOUT</td>
<td></td>
<td>1.4</td>
<td>3.0</td>
<td></td>
<td>%</td>
</tr>
<tr>
<td>$dq$</td>
<td>Differential Phase CVOUT</td>
<td></td>
<td>0.7</td>
<td>1.5</td>
<td></td>
<td>%</td>
</tr>
<tr>
<td>THD</td>
<td>Output Distortion VOUT=1.4Vpp at 3.58MHz</td>
<td></td>
<td>0.3</td>
<td></td>
<td></td>
<td>%</td>
</tr>
<tr>
<td>$X_{TALK}$</td>
<td>Crosstalk VOUT=1.4Vpp at 3.58MHz</td>
<td></td>
<td>-50</td>
<td></td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>SNR</td>
<td>SNR Channel CVOUT</td>
<td>NTC-7 Weighting 4.2MHz Low-Pass V_IN=714mV, V_OUT=1.428Vpp/1.010Vrms</td>
<td>70</td>
<td>75</td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>SNR EQ_NOTCH</td>
<td>Channel SNR EQ_NOTCH from 400kHz to 4.2MHz</td>
<td></td>
<td>65</td>
<td>70</td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>$t_{pd}$</td>
<td>Propagation Delay at 400kHz</td>
<td></td>
<td>112</td>
<td></td>
<td></td>
<td>ns</td>
</tr>
<tr>
<td>GD</td>
<td>Group Delay CVOUT at 3.58MHz (Reference to 400kHz)</td>
<td></td>
<td>-5</td>
<td>0</td>
<td>5</td>
<td>ns</td>
</tr>
<tr>
<td>$t_{CLGCV}$</td>
<td>Chroma-Luma Gain CVOUT f=3.58MHz (Reference to 400kHz)</td>
<td></td>
<td>98</td>
<td>100</td>
<td>102</td>
<td>%</td>
</tr>
<tr>
<td>$t_{CLDCV}$</td>
<td>Chroma-Luma Delay CVOUT f=3.58MHz (Reference to 400kHz)</td>
<td></td>
<td>-10</td>
<td>0</td>
<td>10</td>
<td>ns</td>
</tr>
<tr>
<td>$t_{GDEQ}$</td>
<td>Group Delay EQ_NOTCH f=3.58MHz (Reference to 400kHz)</td>
<td></td>
<td>-195</td>
<td>-180</td>
<td>-165</td>
<td>ns</td>
</tr>
<tr>
<td>$t_{CLGEQ}$</td>
<td>Chroma-Luma Gain EQ_NOTCH f=3.58MHz (Reference to 400kHz)</td>
<td></td>
<td>95</td>
<td>100</td>
<td>105</td>
<td>%</td>
</tr>
<tr>
<td>$t_{CLDEQ}$</td>
<td>Chroma-Luma Delay EQ_NOTCH f=3.58MHz (Reference to 400kHz)</td>
<td></td>
<td>-195</td>
<td>-180</td>
<td>-165</td>
<td>ns</td>
</tr>
<tr>
<td>$dGEQ$</td>
<td>Differential Gain EQ_NOTCH Channel</td>
<td></td>
<td>0.3</td>
<td>1.0</td>
<td></td>
<td>%</td>
</tr>
<tr>
<td>$dq_{EQ}$</td>
<td>Differential Phase EQ_NOTCH Channel</td>
<td></td>
<td>0.30</td>
<td>0.75</td>
<td></td>
<td>%</td>
</tr>
<tr>
<td>MCF</td>
<td>Modulator Channel Flatness EQ_NOTCH from 400kHz to 3.75MHz</td>
<td></td>
<td>-0.5</td>
<td>0</td>
<td>0.5</td>
<td>dB</td>
</tr>
<tr>
<td>AVPK</td>
<td>Gain Peaking EQ_NOTCH from &gt;3.75MHz to 4.2MHz</td>
<td></td>
<td>-0.5</td>
<td>0</td>
<td>0.5</td>
<td>dB</td>
</tr>
<tr>
<td>Atten1</td>
<td>Notch Attenuation 1 EQ_NOTCH at 4.425MHz</td>
<td></td>
<td>14</td>
<td></td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>Atten2</td>
<td>Notch Attenuation 2 EQ_NOTCH at 4.5MHz</td>
<td></td>
<td>20</td>
<td></td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>Atten3</td>
<td>Notch Attenuation 3 EQ_NOTCH at 4.6MHz</td>
<td></td>
<td>14</td>
<td></td>
<td></td>
<td>dB</td>
</tr>
<tr>
<td>$t_{PASS}$</td>
<td>Passband Group Delay EQ_NOTCH f=400kHz to f=3MHz</td>
<td></td>
<td>-35</td>
<td>35</td>
<td></td>
<td>ns</td>
</tr>
</tbody>
</table>
Typical Performance Characteristics

Unless otherwise noted, $T_A = 25^\circ\text{C}$, $V_{CC} = 5.0\text{V}$, $R_s = 37.5\Omega$, and AC-coupled output into $150\Omega$ load, $CV_{OUT}$.

![Figure 3. Frequency Response](image)

![Figure 4. Group Delay vs. Frequency](image)

![Figure 5. Differential Gain](image)

![Figure 6. Differential Phase](image)

![Figure 7. Noise vs. Frequency](image)
Typical Performance Characteristics

Unless otherwise noted, \( T_A = 25^\circ\text{C}, \ V_{CC} = 5.0\text{V}, \ R_s = 37.5\Omega, \) and AC-coupled output into 150\( \Omega \) load, CV\(_{OUT}\).

**Figure 8.** Modulator vs. Frequency Response

**Figure 9.** Delay Modulator Output

**Figure 10.** Differential Gain, MOD\(_{OUT}\)

**Figure 11.** Differential Phase, MOD\(_{OUT}\)

**Figure 12.** Noise vs. Frequency Modulator Channel

**Figure 13.** Group Delay vs. Frequency
Applications Information

Layout Considerations

General layout and supply bypassing play a major role in high-frequency performance and thermal characteristics. Fairchild offers a four-layer board with full power and ground planes board to guide layout and aid device evaluation. Following this layout configuration provides optimum performance and thermal characteristics for the device. For best results, follow the steps and recommended routing rules below.

Recommended Routing / Layout Rules

- Do not run analog and digital signals in parallel.
- Use separate analog and digital power planes to supply power.
- Traces must run on top of the ground plane.
- No trace should run over ground/power splits.
- Avoid routing at 90-degree angles.
- Minimize clock and video data trace length differences.
- Include 10μF and 0.1μF ceramic power supply bypass capacitors.
- Place the 0.1μF capacitor within 2.54mm (0.1in) of the device power pin.
- Place the 10μF capacitor within 19.05mm (0.75in) of the device power pin.
- For multi-layer boards, use a large ground plane to help dissipate heat.
- For two-layer boards, use a ground plane that extends beyond the device body at least 12.7mm (0.5in) on all sides. Include a metal paddle under the device on the top layer.
- Minimize all trace lengths to reduce series inductance.

Output Considerations

The outputs are DC offset from the input by 150mV; therefore, V_{OUT} = 2 \times V_{IN} + 150mV. This offset is required for optimal performance from the output driver and is held at the minimum value to decrease the standing DC current into the load. Since the FMS6404 has a 2 \times (6dB) gain, the output is typically connected via a 75Ω-series back-matching resistor, followed by the 75Ω video cable. Due to the inherent divide-by-two of this configuration, the blanking level at the load of the video signal is always less than 1V. When AC-coupling the output, ensure that the coupling capacitor passes the lowest frequency content in the video signal and that line time distortion (video tilt) is kept as low as possible. The selection of the coupling capacitor is a function of the subsequent circuit input impedance and the leakage current of the input being driven. To obtain the highest quality output video signal, the series termination resistor must be placed as close to the device output pin as possible. This greatly reduces the parasitic capacitance and inductance effect on the output driver. The distance from the device pin to the series termination resistor should be no greater than 2.54mm (0.1in).

Thermal Considerations

Since the interior of most systems, such as set-top boxes, TVs, and DVD players; is at +70°C; consideration must be given to providing an adequate heat sink for the device package for maximum heat dissipation. When designing a system board, determine how much power each device dissipates. Ensure that devices of high power are not placed in the same location, such as directly above (top plane) or below (bottom plane) each other on the PCB.

PCB Thermal Layout Considerations

- Understand the system power requirements and environmental conditions.
- Maximize thermal performance of the PCB.
- Consider using 70μm of copper for high-power designs.
- Make the PCB as thin as possible by reducing FR4 thickness.
- Use vias in power pad to tie adjacent layers together.
- Remember that baseline temperature is a function of board area, not copper thickness.
- Modeling techniques provide a first-order approximation.
Physical Dimensions

Figure 15. 8-Lead, Small-Outline Integrated Circuit (SOIC), JEDEC MS-012, .150" Narrow Body

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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GTO™
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ISOLPLANAR™
Makewell™
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MegaBuck™
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MiPakIT™
MotionDrive™
MotionMax™
Motion-SPM™
miServer™
OptiHi™
OPTOLOGIC™
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<table>
<thead>
<tr>
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<th>Product Status</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Advance Information</td>
<td>Formative / In Design</td>
<td>Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.</td>
</tr>
<tr>
<td>Preliminary</td>
<td>First Production</td>
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</tr>
<tr>
<td>No Identification Needed</td>
<td>Full Production</td>
<td>Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.</td>
</tr>
<tr>
<td>Obsolete</td>
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</tr>
</tbody>
</table>

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